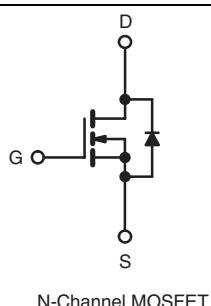
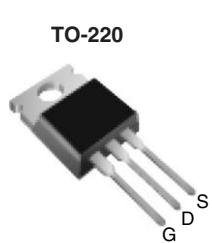


Power MOSFET

PRODUCT SUMMARY		
V _{DS} (V)	500	
R _{DS(on)} (Ω)	V _{GS} = 10 V	0.26
Q _g (Max.) (nC)	120	
Q _{gs} (nC)	34	
Q _{gd} (nC)	54	
Configuration	Single	



FEATURES

- Low Gate Charge Q_g Results in Simple Drive Requirement
- Improved Gate, Avalanche and Dynamic dV/dt Ruggedness
- Fully Characterized Capacitance and Avalanche Voltage and Current
- Low R_{DS(on)}
- Lead (Pb)-free Available


RoHS*
COMPLIANT

APPLICATIONS

- Switch Mode Power Supply (SMPS)
- Uninterruptible Power Supply
- High Speed Power Switching
- Hard Switched and High Frequency Circuits

ORDERING INFORMATION

Package	TO-220
Lead (Pb)-free	IRFB18N50KPbF SiHFB18N50K-E3
SnPb	IRFB18N50K SiHFB18N50K

ABSOLUTE MAXIMUM RATINGS T_C = 25 °C, unless otherwise noted

PARAMETER	SYMBOL	LIMIT	UNIT
Drain-Source Voltage	V _{DS}	500	V
Gate-Source Voltage	V _{GS}	± 30	
Continuous Drain Current	I _D	17	A
		11	
Pulsed Drain Current ^a	I _{DM}	68	
Linear Derating Factor		1.8	W/°C
Single Pulse Avalanche Energy ^b	E _{AS}	370	mJ
Repetitive Avalanche Current ^a	I _{AR}	17	A
Repetitive Avalanche Energy ^a	E _{AR}	22	mJ
Maximum Power Dissipation	P _D	220	W
Peak Diode Recovery dV/dt ^c	dV/dt	7.8	V/ns
Operating Junction and Storage Temperature Range	T _J , T _{stg}	- 55 to + 150	°C
Soldering Recommendations (Peak Temperature)	for 10 s	300 ^d	
Mounting Torque	6-32 or M3 screw	10	N

Notes

- Repetitive rating; pulse width limited by maximum junction temperature.
- Starting T_J = 25 °C, L = 2.5 mH, R_G = 25 Ω, I_{AS} = 17 A.
- I_{SD} ≤ 17 A, dI/dt ≤ 376 A/μs, V_{DD} ≤ V_{DS}, T_J ≤ 150 °C.
- 1.6 mm from case.

* Pb containing terminations are not RoHS compliant, exemptions may apply

THERMAL RESISTANCE RATINGS

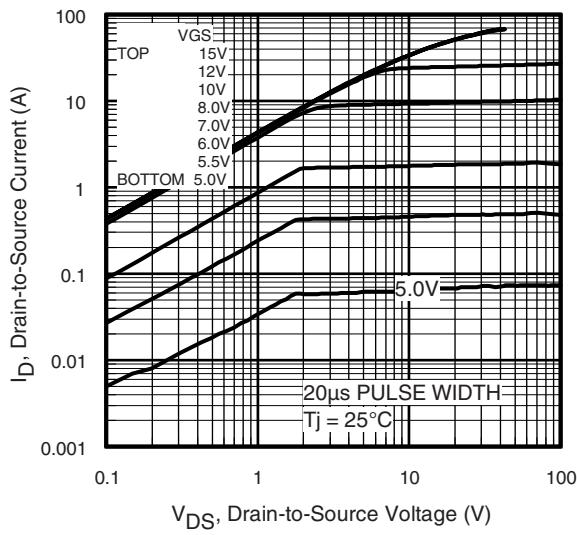
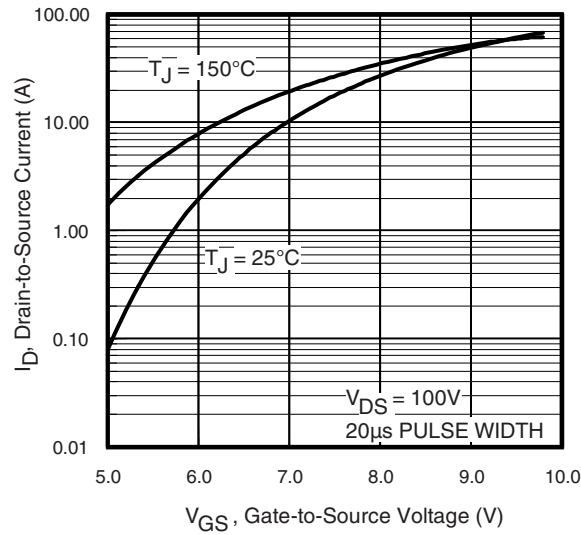
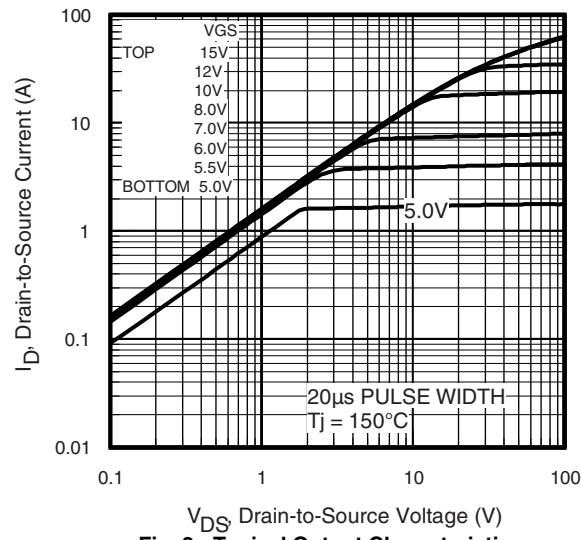
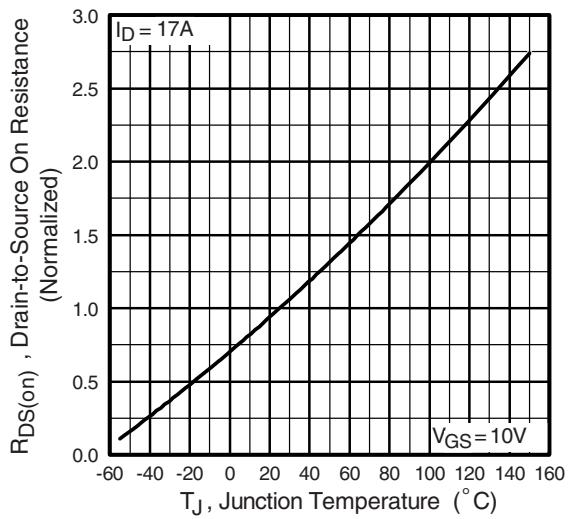
PARAMETER	SYMBOL	TYP.	MAX.	UNIT
Maximum Junction-to-Ambient ^a	R _{thJA}	-	58	°C/W
Case-to-Sink, Flat, Greased Surface	R _{thCS}	0.50	-	
Maximum Junction-to-Case (Drain) ^a	R _{thJC}	-	0.56	

Notea. R_{th} is measured at T_J approximately 90 °C.**SPECIFICATIONS** T_J = 25 °C, unless otherwise noted

PARAMETER	SYMBOL	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
Static							
Drain-Source Breakdown Voltage	V _{DS}	V _{GS} = 0 V, I _D = 250 μA		500	-	-	V
V _{DS} Temperature Coefficient	ΔV _{DS} /T _J	Reference to 25 °C, I _D = 1 mA		-	0.59	-	V/°C
Gate-Source Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA		3.0	-	5.0	V
Gate-Source Leakage	I _{GSS}	V _{GS} = ± 30 V		-	-	± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 500 V, V _{GS} = 0 V		-	-	50	μA
		V _{DS} = 400 V, V _{GS} = 0 V, T _J = 125 °C		-	-	250	
Drain-Source On-State Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 10 A ^b	-	0.26	0.29	Ω
Forward Transconductance	g _{fs}	V _{DS} = 50 V, I _D = 10 A		6.4	-	-	S
Dynamic							
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1.0 MHz, see fig. 5		-	2830	-	pF
Output Capacitance	C _{oss}			-	330	-	
Reverse Transfer Capacitance	C _{rss}			-	38	-	
Output Capacitance	C _{oss}	V _{GS} = 0 V	V _{DS} = 1.0 V, f = 1.0 MHz	-	3310	-	nC
			V _{DS} = 400 V, f = 1.0 MHz	-	93	-	
Effective Output Capacitance	C _{oss eff.}		V _{DS} = 0 V to 400 V ^c	-	155	-	
Total Gate Charge	Q _g	I _D = 17 A, V _{DS} = 400 V, see fig. 6 and 13 ^b		-	-	120	ns
Gate-Source Charge	Q _{gs}			-	-	34	
Gate-Drain Charge	Q _{gd}			-	-	54	
Turn-On Delay Time	t _{d(on)}	V _{GS} = 10 V		-	22	-	ns
Rise Time	t _r			-	60	-	
Turn-Off Delay Time	t _{d(off)}		V _{DD} = 250 V, I _D = 17 A, R _G = 7.5 Ω, see fig. 10 ^b	-	45	-	
Fall Time	t _f			-	30	-	
Drain-Source Body Diode Characteristics							
Continuous Source-Drain Diode Current	I _S	MOSFET symbol showing the integral reverse p - n junction diode		-	-	17	A
Pulsed Diode Forward Current ^a	I _{SM}			-	-	68	
Body Diode Voltage	V _{SD}	T _J = 25 °C, I _S = 17 A, V _{GS} = 0 V ^b		-	-	1.5	V
Body Diode Reverse Recovery Time	t _{rr}	T _J = 25 °C, I _F = 17 A, dI/dt = 100 A/μs ^b		-	520	780	ns
Body Diode Reverse Recovery Charge	Q _{rr}			-	5.3	8.0	μC
Forward Turn-On Time	t _{on}	Intrinsic turn-on time is negligible (turn-on is dominated by L _S and L _D)					

Notes

- a. Repetitive rating; pulse width limited by maximum junction temperature (see fig. 11).
b. Pulse width ≤ 300 μs; duty cycle ≤ 2 %.
c. C_{oss eff.} is a fixed capacitance that gives the same charging time as C_{oss} while V_{DS} is rising from 0 to 80 % V_{DS}.

TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

Fig. 1 - Typical Output Characteristics

Fig. 3 - Typical Transfer Characteristics

Fig. 2 - Typical Output Characteristics

Fig. 4 - Normalized On-Resistance vs. Temperature

IRFB18N50K, SiHFB18N50K

Vishay Siliconix

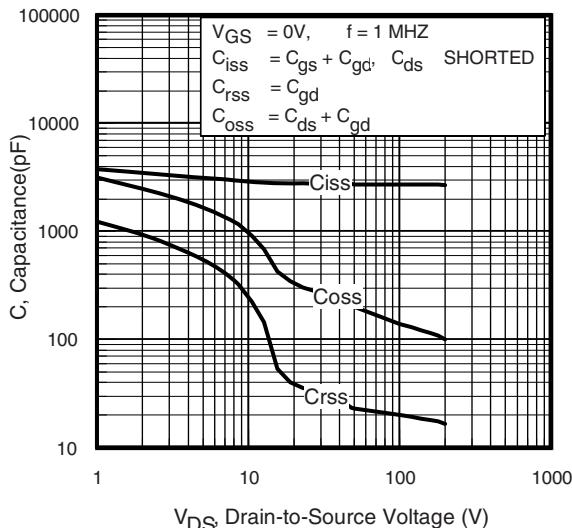


Fig. 5 - Typical Capacitance vs. Drain-to-Source Voltage

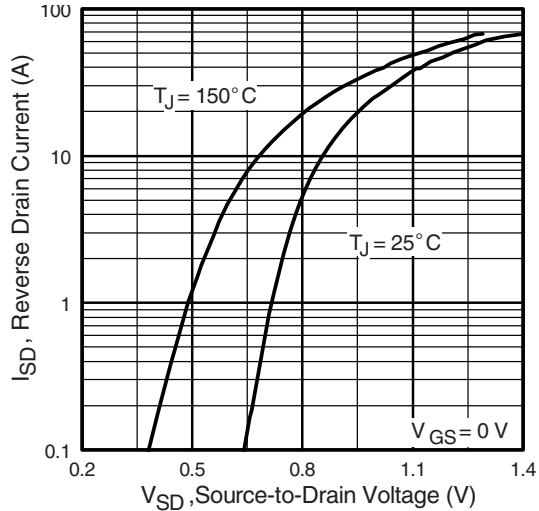


Fig. 7 - Typical Source-Drain Diode Forward Voltage

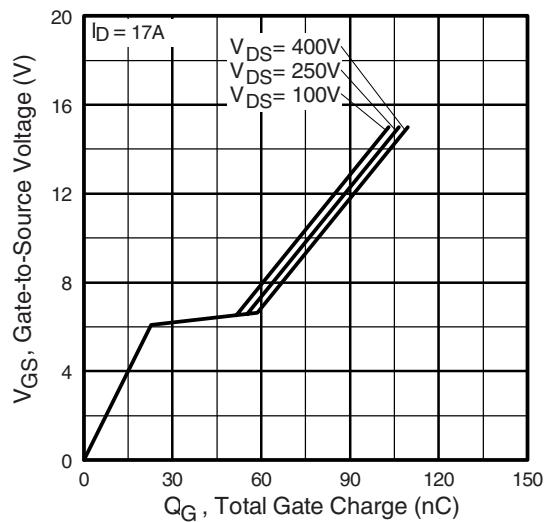


Fig. 6 - Typical Gate Charge vs. Gate-to-Source Voltage

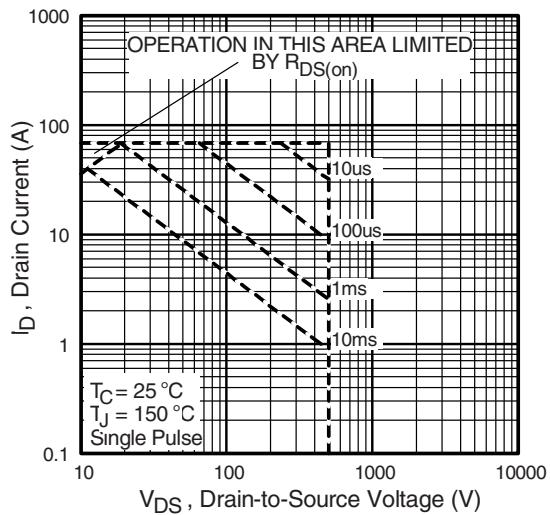


Fig. 8 - Maximum Safe Operating Area

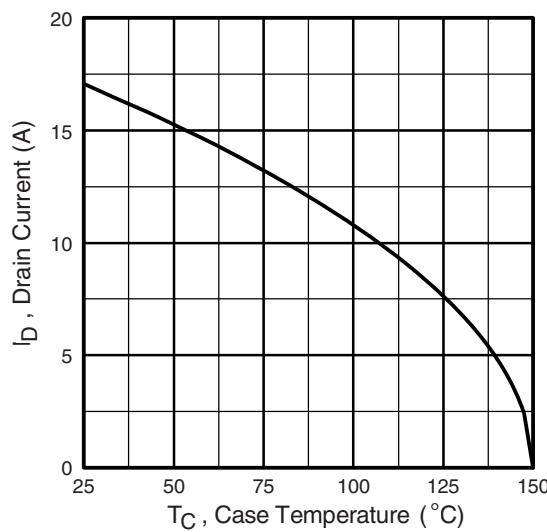


Fig. 9 - Maximum Drain Current vs. Case Temperature

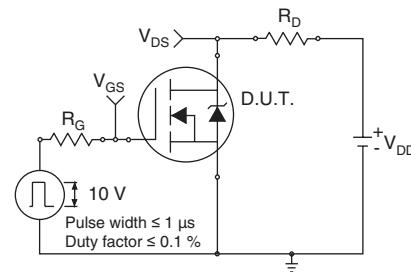


Fig. 10a - Switching Time Test Circuit

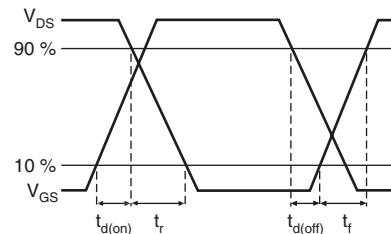


Fig. 10b - Switching Time Waveforms

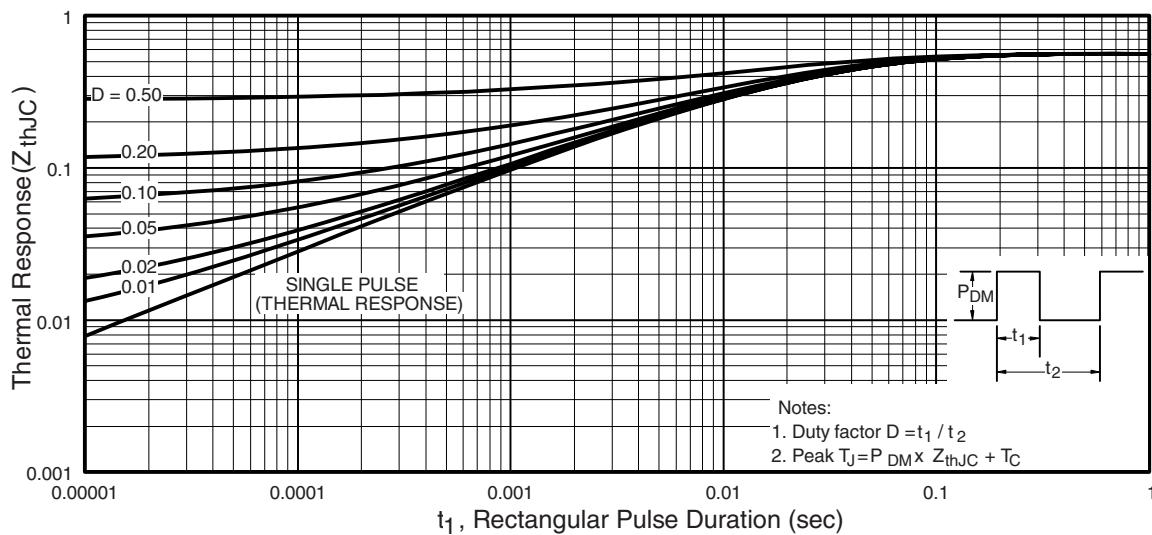


Fig. 11 - Maximum Effective Transient Thermal Impedance, Junction-to-Case

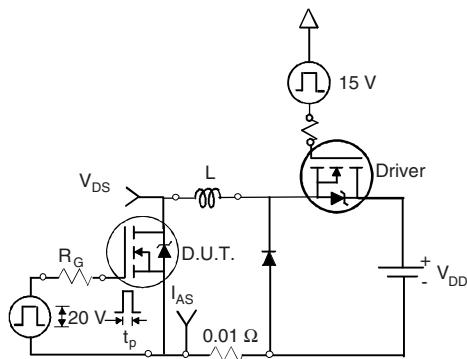


Fig. 12a - Unclamped Inductive Test Circuit

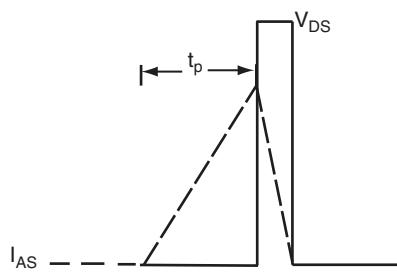


Fig. 12b - Unclamped Inductive Waveforms

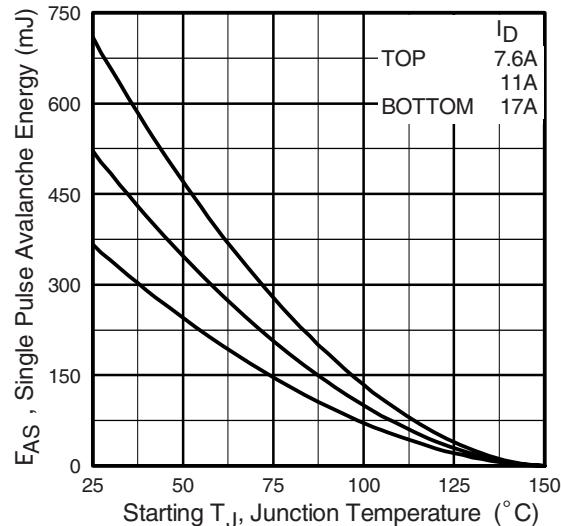


Fig. 12c - Maximum Avalanche Energy vs. Drain Current

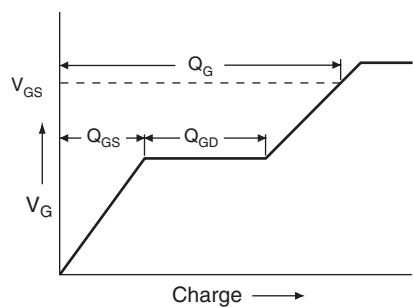


Fig. 13a - Basic Gate Charge Waveform

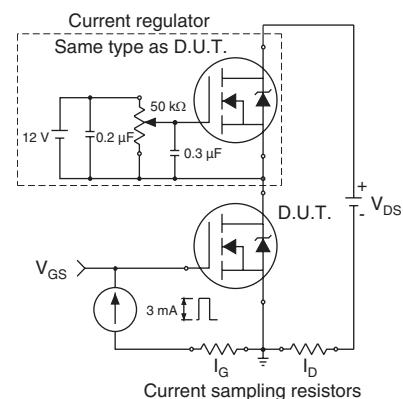
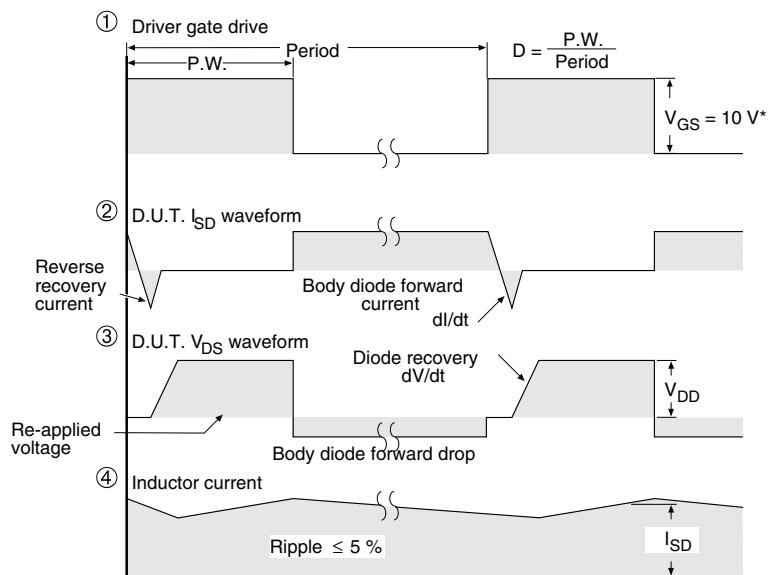
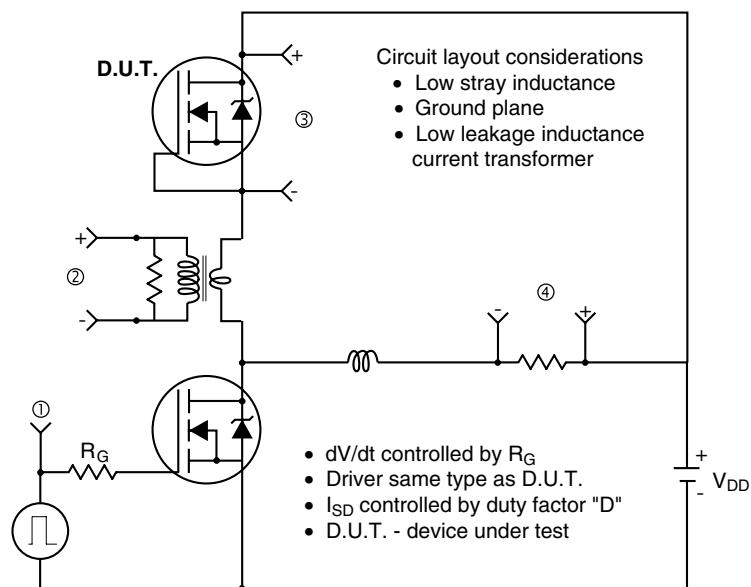


Fig. 13b - Gate Charge Test Circuit

Peak Diode Recovery dV/dt Test Circuit

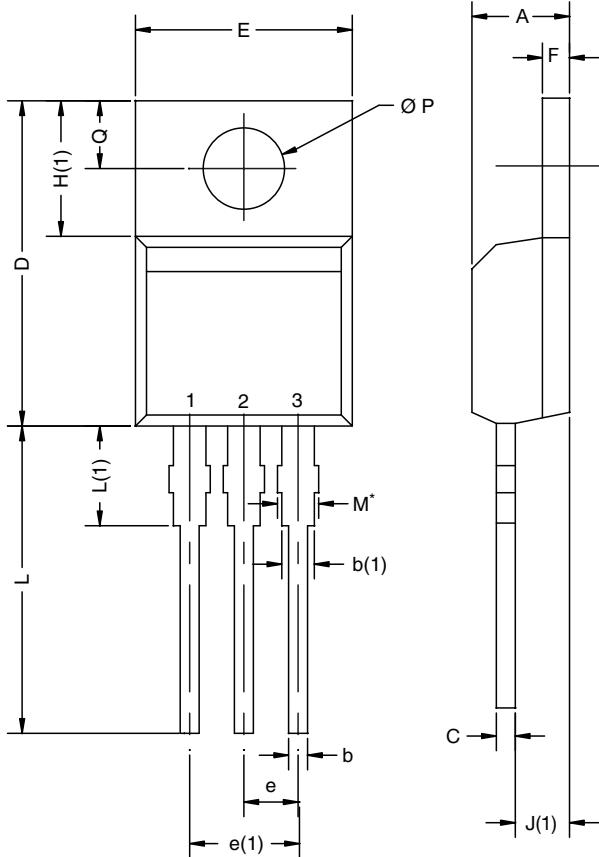


* $V_{GS} = 5$ V for logic level devices

Fig. 14 - For N-Channel

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TO-220AB

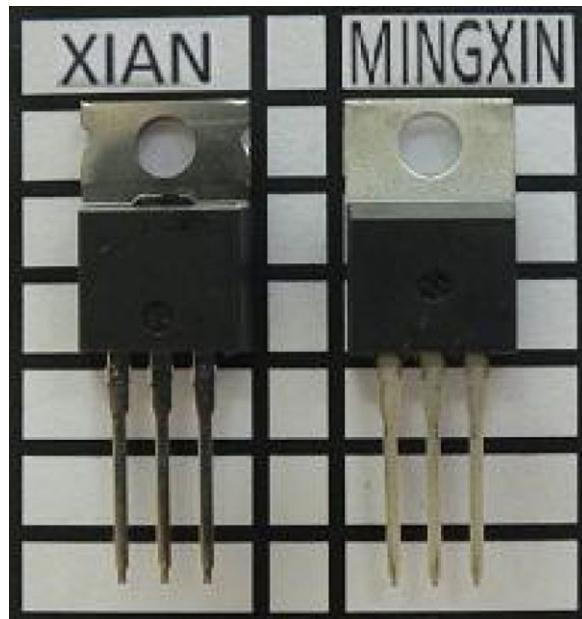


DIM.	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	4.25	4.65	0.167	0.183
b	0.69	1.01	0.027	0.040
b(1)	1.20	1.73	0.047	0.068
c	0.36	0.61	0.014	0.024
D	14.85	15.49	0.585	0.610
E	10.04	10.51	0.395	0.414
e	2.41	2.67	0.095	0.105
e(1)	4.88	5.28	0.192	0.208
F	1.14	1.40	0.045	0.055
H(1)	6.09	6.48	0.240	0.255
J(1)	2.41	2.92	0.095	0.115
L	13.35	14.02	0.526	0.552
L(1)	3.32	3.82	0.131	0.150
Ø P	3.54	3.94	0.139	0.155
Q	2.60	3.00	0.102	0.118

Notes

* M = 1.32 mm to 1.62 mm (dimension including protrusion)
Heatsink hole for HVM

- Xi'an and Mingxin actual photo





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- Поставка сложных, дефицитных, либо снятых с производства позиций;
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- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



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